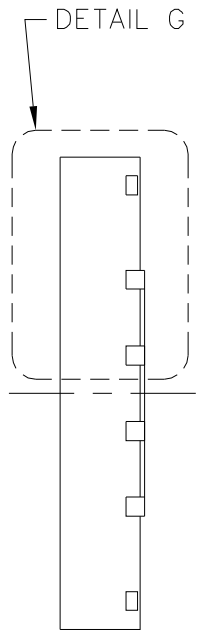
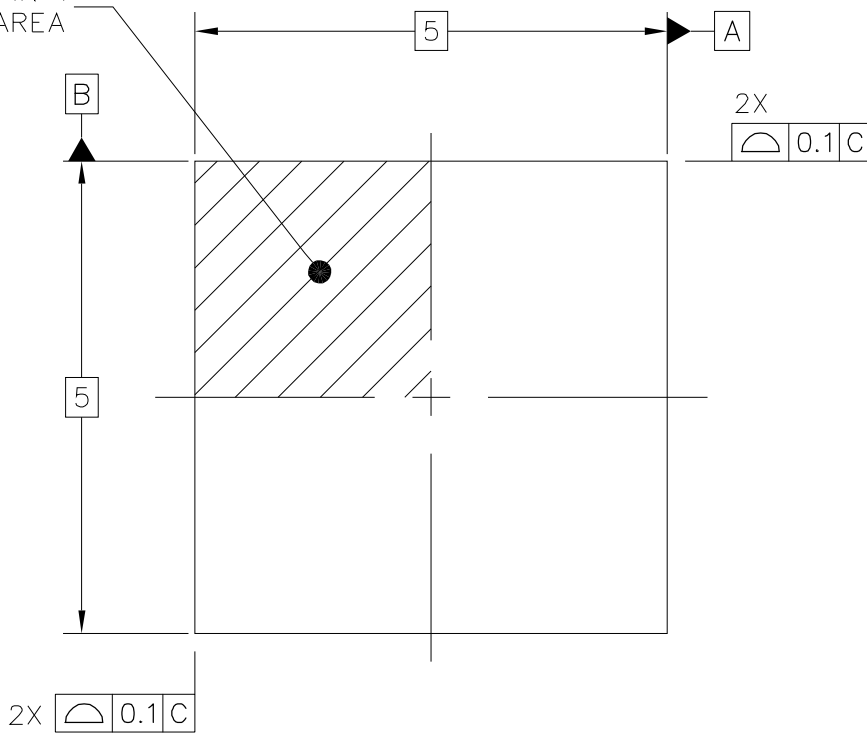
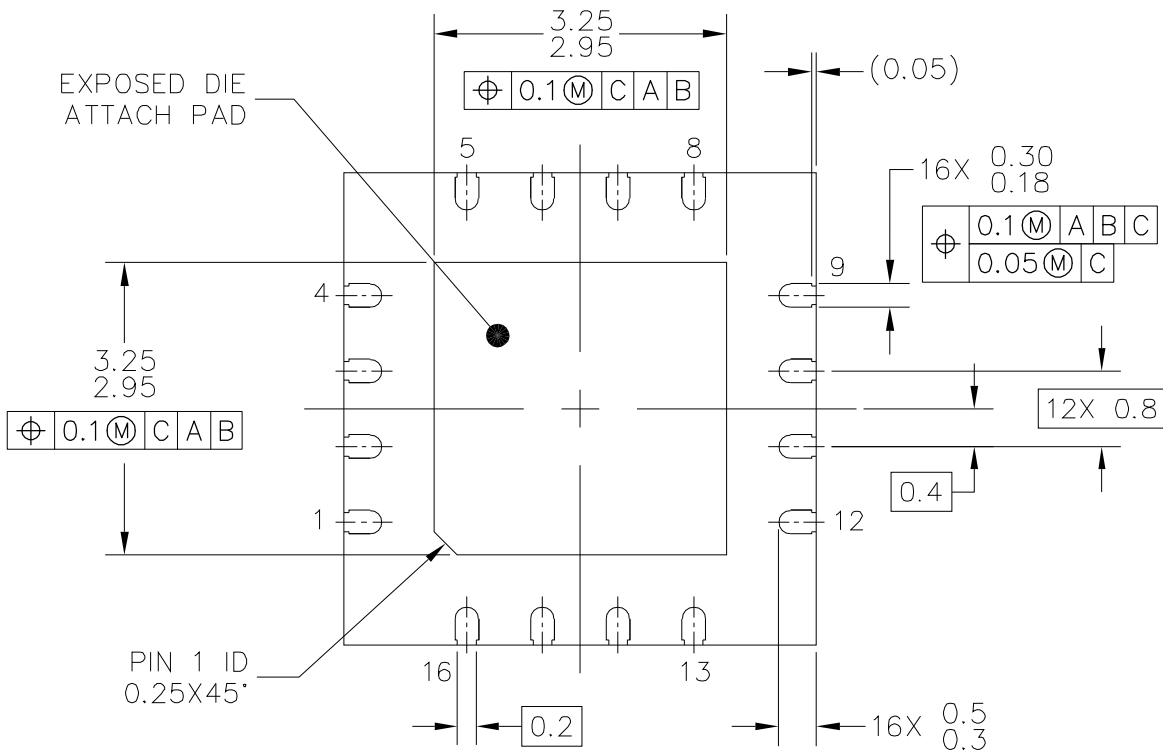




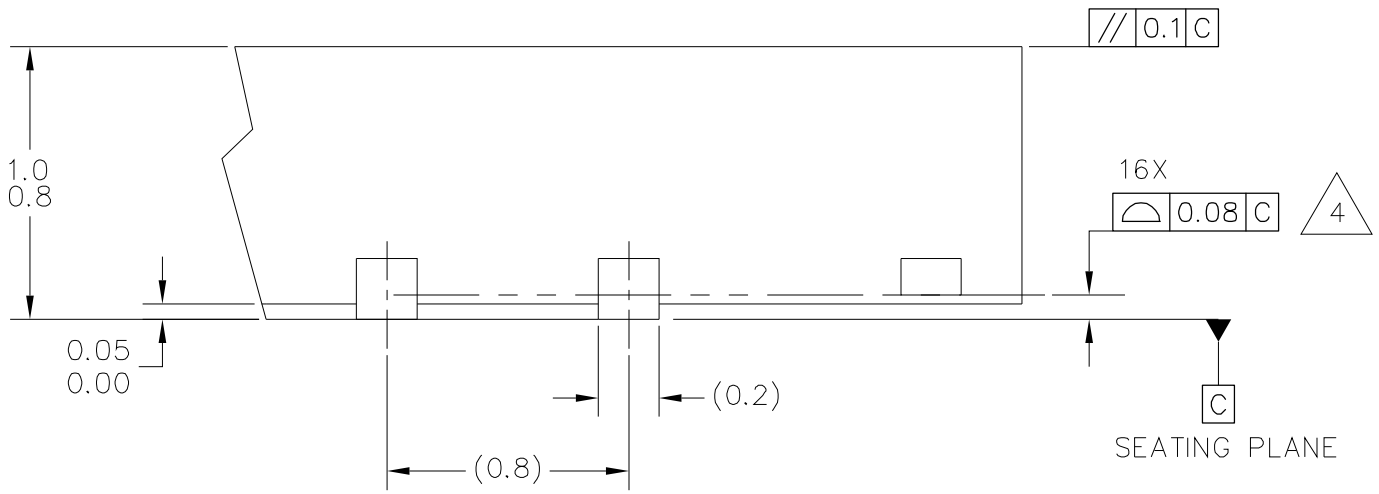
PIN 1
INDEX
AREA



EXPOSED DIE
ATTACH PAD



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TITLE: QFN, THERMALLY ENHANCED, 5 X 5 X 0.9, 0.8 PITCH, 16 TERMINAL	DOCUMENT NO: 98ASA00671D REV: A	
	STANDARD: NON-JEDEC	
	SOT1593-1	20 JAN 2016




DETAIL G
VIEW ROTATED 90°CW

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	STANDARD: NON-JEDEC	
	SOT1593-1	20 JAN 2016



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THIS IS A NON-JEDEC REGISTERED PACKAGE.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH FLAG.
5. MIN. METAL GAP SHOULD BE 0.2 MM.

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		STANDARD: NON-JEDEC	
		SOT1593-1	20 JAN 2016